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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : LEE et al. Confirmation No: 4969
Appl. No. : 10/664,981
Filed : September 22, 2003
Title : SEMICONDUCTOR PACKAGE WITH THERMAL
ENHANCE FILM AND MANUFACTURING METHOD
THEREOF

TC/A.U. : 2815
Examiner : C.C. Chu

Docket No.: : LEEC3073/REF
Customer No: : 23364

AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This is in response to the Official Action of June 16, 2004, in connection with the above-identified application. This response is timely filed.

Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 5 of this paper.